



Title of Change:	Update Notice to FPCN20930ZC - Die Shrink- Guard Ring Width modification.											
Proposed first ship date:	13 April 2018											
Contact information:	Contact your local ON Semiconductor Sales Office or <SitiNurhaza.MohdRamli@onsemi.com>											
Samples:	Contact your local ON Semiconductor Sales Office											
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or < MohdAzizi.Azman@onsemi.com >											
Type of notification:	ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <PCN.Support@onsemi.com>.											
Change category:	<input checked="" type="checkbox"/> Wafer Fab Change <input type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input type="checkbox"/> Other _____											
Change Sub-Category(s):	<input type="checkbox"/> Manufacturing Site Change/Addition <input type="checkbox"/> Material Change <input type="checkbox"/> Datasheet/Product Doc change <input checked="" type="checkbox"/> Manufacturing Process Change <input checked="" type="checkbox"/> Product specific change <input type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Other: _____											
Sites Affected:	<input checked="" type="checkbox"/> All site(s) <input type="checkbox"/> not applicable <input type="checkbox"/> ON Semiconductor site(s) : <input type="checkbox"/> External Foundry/Subcon site(s)											
Description and Purpose:												
This Update Notification announces to customers that Die Shrink- Guard Ring Width change as below:												
<table border="1"> <thead> <tr> <th>Material to be changed</th> <th>Before Change Description</th> <th>After Change Description</th> </tr> </thead> <tbody> <tr> <td>Back metal thickness</td> <td>12kA Au</td> <td>8kA Au</td> </tr> <tr> <td>Die Shrink- Guard Ring Width</td> <td>2mils</td> <td>1mils</td> </tr> </tbody> </table>				Material to be changed	Before Change Description	After Change Description	Back metal thickness	12kA Au	8kA Au	Die Shrink- Guard Ring Width	2mils	1mils
Material to be changed	Before Change Description	After Change Description										
Back metal thickness	12kA Au	8kA Au										
Die Shrink- Guard Ring Width	2mils	1mils										
FPCN20930ZC was previously released to qualify Power Schottky Back Metal Thinning with Die Shrink.												
NOTE: AEC-1pager is attached.												
<p>To access file attachments on pdf copy of PCN, please be guided by the steps below:</p> <ol style="list-style-type: none"> 1. Download pdf copy of the PCN to your computer 2. Open the downloaded pdf copy of the PCN 3. Click on the paper clip icon available on the menu provided in the left/bottom portion of the screen to reveal the Attachment field 4. Then click on the attached file/s 												



List of Affected Standard Parts:

Current Part Number	Qualification Vehicle
NRVB0530T1G	NRVB0540T1G
NRVB0530T3G	
NRVB0540T1G	
NRVB0540T3G	
NRVB130T1G	
NRVB130T3G	
SBR80520LT1G	
SBR80520LT3G	